

DECLARATION AND POWER OF ATTORNEY

As below-named inventor, I hereby DECLARE THAT:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor of the subject matter which is claimed and which a patent is sought on the invention entitled:

**HIGH DENSITY INTEGRATED CIRCUITS AND
THE METHOD OF PACKAGING THE SAME**
the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of the application in accordance with Title 37, Code of Federal Regulations Section 1.56(a).

I do not claim foreign priority benefit under Title 35, United States Code, Section 119 of any foreign application for patent or inventor's certificate.

I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Section 112. I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application: None.

I hereby appoint DAVID W. WONG, 46 Willowbrook Road, Thornhill, Ontario, Canada, L3T 4W9. Registration No. 26,408, my attorney or agent with full power of substitution and revocation to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

I hereby declare that all statement made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Inventor's signature: _____


DANIEL WANG

Date: December 3, 1996

Residence: Markham, Ontario, Canada.

Citizenship: Canada

Post Office Address: 60 Alexis Road, Thornhill,
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Daniel Wang

Examiner: Unassigned

Serial No:

Group Art Unit:

Filed: January 25, 2002

Docket: 669-77 CON

For: HIGH DENSITY INTEGRATED
CIRCUITS AND THE METHOD OF
PACKAGING THE SAME

Commissioner for Patents
Washington, D.C. 20231

**POWER OF ATTORNEY BY INVENTOR(S)
(REVOCATION OF PRIOR POWERS)**

As named inventor(s) for the above identified

application,
 patent,

REVOCATION OF PRIOR POWERS OF ATTORNEY

We hereby revoke all powers of attorney previously given and

NEW POWER OF ATTORNEY

We hereby appoint the following attorney(s) and/or agent(s) to prosecute and transact all business in the Patent and Trademark Office connected therewith.

Charles R. Hoffmann, Reg. No. 24,102; Ronald J. Baron, Reg. No. 29,281; Gerald T. Bodner, Reg. No. 30,449; Alan M. Sack, Reg. No. 31,874; A. Thomas Kammer, Reg. No. 28,226; R. Glenn Schroeder, Reg. No. 34,720; Glenn T. Henneberger, Reg. No. 36,074; Irving N. Feit, Reg. No. 28,601; Anthony E. Bennett, Reg. No. 40,910; Gregory W. Bachmann, Reg. No. 41,593; Steven T. Zuschlag, Reg. No. 43,309; Susan A. Sipos, Reg. No. 43,128; Kevin E. McDermott, Reg. No. 35,946; Rod S. Turner, Reg. No. 38,639; Robert C. Morrise, Reg. No. 42,910; James F. Harrington, Reg. No. 44,741; Algis Anillionis, Reg. No. 36,995; Justin K. Holmes, Reg. No. 42,666; and Lauren T. Emr, Reg. No. 46,139 each of them of HOFFMANN & BARON, LLP, 6900 Jericho Turnpike, Syosset, New York 11791; and Daniel A. Scola, Jr., Reg. No. 29,855; Salvatore J. Abbruzzese, Reg. No. 30,152; John Sopko, Reg. No. 41,321; Gloria K. Szakiel, Reg. No. 45,149; Mark E. Baron, Reg. No. 46,150; Ludomir A. Budzyn, Reg. No. 40,540; Christina L. Warrick, Reg. No. 45,690; Linda T. Parker, Reg. No. 46,046; Robert M. Rodrick, Reg. No. 27,086; Rohini K. Garg, Reg. No. 45,272; Anna-Lisa Gallo, Reg. No. P-50,279; and Joy I. Farber, Reg. No. 44,103, each of them of HOFFMANN & BARON, LLP, 1055 Parsippany Boulevard, Parsippany, New Jersey 07054.

SEND CORRESPONDENCE TO:

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SIGNATURE(S)

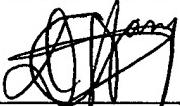
Applicant:

Microbonds, Inc.
Daniel Wang, President & CEO

Applicant's Address:

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Date: Feb. 14, 2002 Signature


Daniel Wang, President & CEO
Microbonds, Inc.
